

ABSTRACT OF THE DISCLOSURE

In a semiconductor device in which a second semiconductor chip is layered on a first semiconductor chip mounted on a substrate, a mounting-use bonding layer being formed on a reverse surface of the second semiconductor chip with respect to a circuit formation thereof, the mounting-use bonding layer functions as a bonding agent and as a supporting member for supporting protruded part of the second semiconductor chip, which is protruded from an outer edge of the first semiconductor chip. In this semiconductor device, it is possible to bond the second semiconductor chip and the substrate stably by wire bonding.